

[TABLE-1]

FIRST DIGIT	SECOND DIGIT	THIRD DIGIT	FOURTH DIGIT	FIFTH DIGIT
YEAR	MARKING	MONTH	MARKING	DAY
2016	6	1	1	1
2017	7	2	2	2
2018	8	3	3	3
2019	9	4	4	4
2020	0	5	5	5
2021	1	6	6	6
2022	2	7	7	7
2023	3	8	8	8
2024	4	9	9	9
2025	5	10	0	10
·	·	11	X	11
·	·	12	Y	12
·	·	·	·	13
·	·	·	·	14
·	·	·	·	15
·	·	·	·	16
·	·	·	·	17
·	·	·	·	18
·	·	·	·	19
·	·	·	·	20
·	·	·	·	21
·	·	·	·	22
·	·	·	·	23
·	·	·	·	24
·	·	·	·	25
·	·	·	·	26
·	·	·	·	27
·	·	·	·	28
·	·	·	·	29
·	·	·	·	30
·	·	·	·	31
·	·	·	·	32
·	·	·	·	33

NOTE 1. COPLANARITY OF SMT TERMINAL AND BRACKET SHALL BE 0.1 MAXIMUM.
 NOTE 2. MATING DIMENSIONS CONSIST OF "Universal Serial Bus Type-C Cable and Connector Specification 1.2"
 NOTE 3. THE SHELL LENGTH IS LESS THAN THE 6.2MM RECOMMENDED IN THE USB STANDARD. THE SYSTEM IMPLEMENTER IS RESPONSIBLE FOR ACHIEVING END PRODUCT RELIABILITY FOR THE MATED CONNECTOR CONDITION. REFER TO USB TYPE-C CABLE AND CONNECTOR SPECIFICATION REVISION 1.2 SECTION 3.2.1 NOTE 7.
 NOTE 4. VACUUM AREA.
 NOTE 5. THIS DIMENSION IS SET AT MAXIMUM RATE OF THE SPRING STICKING OUT WHEN MATING WITH PLUG.
 NOTE 6. PRODUCTION LOT NUMBER IS MARKED AS SHOWN IN TABLE-1. (LASER MARKING)
 NOTE 7. METAL EXPOSED AREA SIZE COULD BE SLIGHTLY CHANGED BASED ON MOLDING PROCESS CONDITION IN EACH LOT, HOWEVER THIS WOULD NOT AFFECT CONNECTOR FUNCTION.
 NOTE 8. CONVEX OF LASER WELDING POINT SHOULD BE 0.15 OR LESS.
 NOTE 9. LASER WELD POINTS MAY BE DISCOLORED.
 NOTE 10. PIN ASSIGNMENT (FRONT VIEW)

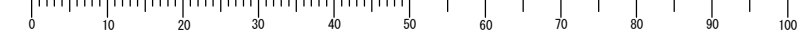
Pin No.	A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
	GND	TX1+	TX1-	V _{BUS}	CC1	D+	D-	SBU1	V _{BUS}	RX2-	RX2+	GND
Pin No.	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1
	GND	RX1+	RX1-	V _{BUS}	SBU2	D-	D+	CC2	V _{BUS}	TX2-	TX2+	GND

6	SHELL	1	STAINLESS STEEL	NICKEL PLATING	NICKLE: 0.5 μm MIN.
5	MID PLATE	1	STAINLESS STEEL	NICKEL PLATING	NICKLE: 0.5 μm MIN.
4	BRACKET	1	STAINLESS STEEL	NICKEL PLATING	NICKLE: 0.5 μm MIN.
3	INSULATOR	1	HEAT RESISRING PLASTIC	—	COLOR:BLACK
2	CONTACT B	12	COPPER ALLOY	CONTACT AREA: GOLD OVER NICKEL SOLDER TAILS: GOLD FLASH OVER NICKEL	CONTACT AREA: NICKEL-1.5 μm MIN. GOLD:0.1 μm MIN. SOLDER TAILS: NICKEL-1.5 μm MIN. GOLD FLASH:0.03 μm MIN.
1	CONTACT A	12	COPPER ALLOY	CONTACT AREA: GOLD OVER NICKEL SOLDER TAILS: GOLD FLASH OVER NICKEL	CONTACT AREA: NICKEL-1.5 μm MIN. GOLD:0.1 μm MIN. SOLDER TAILS: NICKEL-1.5 μm MIN. GOLD FLASH:0.03 μm MIN.

仕様書 (SPECIFICATION)	第1版 (ORIGINAL DATE)	尺度 (SCALE)	シリーズ (SERIES)
JACS-30353	26/MAR/2018	5:1	DX07
一般公差 (GENERAL TOLERANCE)	製図 DR.	名称 (TITLE)	備考 (REMARKS)
寸法 (DIMENSION):	担当 CHK.	DX07BN24JA2	
· ±0.8	Y. SATOU		
× ±0.4	査閲 APPD.		
·× ±0.1	承認 APPD.		
·×× ±	T. MASUMOTO		
単位 (UNIT): mm			
	質量 (MASS)		



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